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PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM	FILING DATE	CLASS	SUBCLASS	GAU	EXAMINER
10081661	02/22/2002	438	537	2812	Nguyen Ha

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****CONTINUING DATA VERIFIED:**

**** FOREIGN APPLICATIONS VERIFIED:**
REPUBLIC OF KOREA 01-25573 05/10/2001

PG-PUB	DO NOT PUBLISH <input type="checkbox"/>	RESCIND <input type="checkbox"/>
Foreign priority claimed <input type="checkbox"/> yes <input type="checkbox"/> no		ATTORNEY DOCKET NO
35 USC 119 conditions met <input type="checkbox"/> yes <input type="checkbox"/> no		SAM-0313
Verified and Acknowledged Examiners's initials		
TITLE : Method of manufacturing interconnection line in semiconductor device		

U.S. DEPT. OF COMM./PAT. & TM.-PTO-4361 (Rev. 12-94)

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
		Total Claims	Print Claim for O.G.
ISSUE FEE		DRAWING	
Amount Due	Date Paid	Sheets Drwg.	Figs. Drwg.
			Print Fig.
		Applicati n Examiner	
<input type="checkbox"/> TERMINAL DISCLAIMER		PREPARED FOR ISSUE	
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